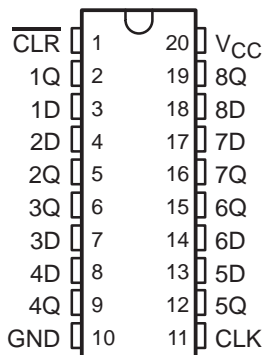
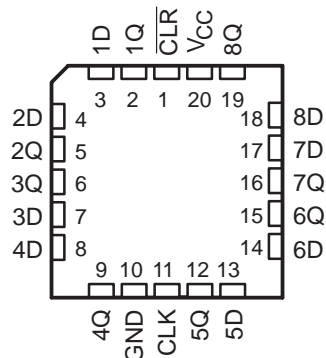


SN54HC273 . . . J OR W PACKAGE
SN74HC273 . . . DB, DW, N, NS, OR PW PACKAGE
(TOP VIEW)



SN54HC273 . . . FK PACKAGE
(TOP VIEW)



description/ordering information

These circuits are positive-edge-triggered D-type flip-flops with a direct clear ($\overline{\text{CLR}}$) input.

ORDERING INFORMATION

T _A	PACKAGE†		ORDERABLE PART NUMBER	TOP-SIDE MARKING
-40°C to 85°C	PDIP – N	Tube of 20	SN74HC273N	SN74HC273N
	SOIC – DW	Tube of 25	SN74HC273DW	HC273
		Reel of 2000	SN74HC273DWR	
	SOP – NS	Reel of 2000	SN74HC273NSR	HC273
	SSOP – DB	Reel of 2000	SN74HC273DBR	HC273
	TSSOP – PW	Tube of 70	SN74HC273PW	HC273
		Reel of 2000	SN74HC273PWR	
Reel of 250		SN74HC273PWT		
-55°C to 125°C	CDIP – J	Tube of 20	SNJ54HC273J	SNJ54HC273J
	CFP – W	Tube of 85	SNJ54HC273W	SNJ54HC273W
	LCCC – FK	Tube of 55	SNJ54HC273FK	SNJ54HC273FK

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



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PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

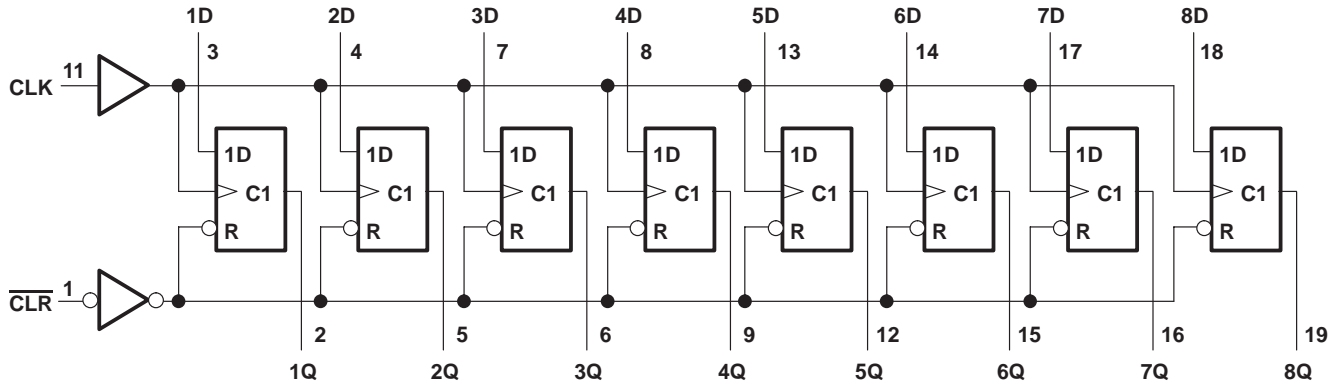


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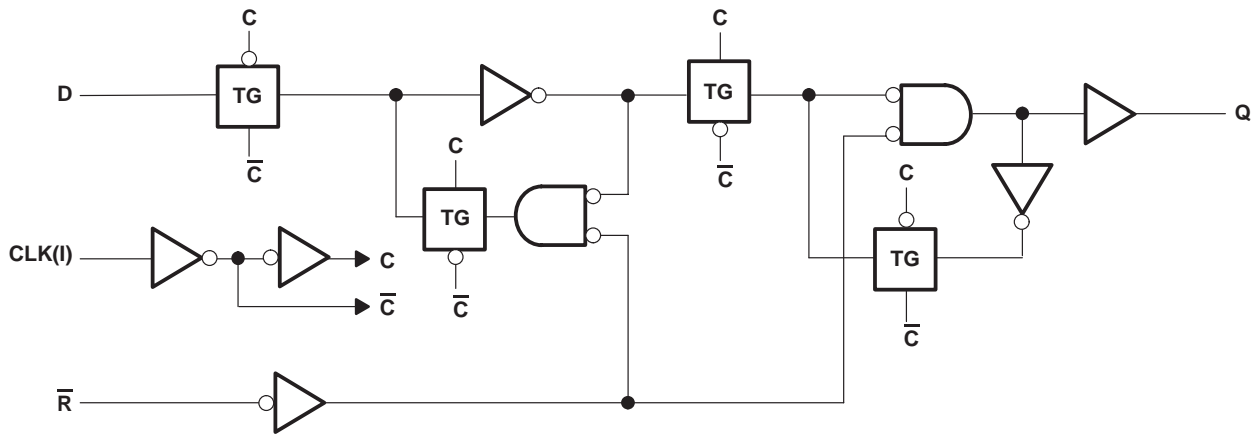
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On products compliant to MIL-PRF-38535, all parameters are tested unless otherwise noted. On all other products, production processing does not necessarily include testing of all parameters.

H	↑	H	H
H	↑	L	L
H	L	X	Q_0

logic diagram (positive logic)



logic diagram, each flip-flop (positive logic)



**TEXAS
INSTRUMENTS**

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† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.
2. The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions (see Note 3)

			SN54HC273			SN74HC273			UNIT
			MIN	NOM	MAX	MIN	NOM	MAX	
V_{CC}	Supply voltage		2	5	6	2	5	6	V
V_{IH}	High-level input voltage	$V_{CC} = 2\text{ V}$	1.5			1.5			V
		$V_{CC} = 4.5\text{ V}$	3.15			3.15			
		$V_{CC} = 6\text{ V}$	4.2			4.2			
V_{IL}	Low-level input voltage	$V_{CC} = 2\text{ V}$			0.5			0.5	V
		$V_{CC} = 4.5\text{ V}$			1.35			1.35	
		$V_{CC} = 6\text{ V}$			1.8			1.8	
V_I	Input voltage		0		V_{CC}	0		V_{CC}	V
V_O	Output voltage		0		V_{CC}	0		V_{CC}	V
$\Delta t/\Delta v$	Input transition rise/fall time	$V_{CC} = 2\text{ V}$			1000			1000	ns
		$V_{CC} = 4.5\text{ V}$			500			500	
		$V_{CC} = 6\text{ V}$			400			400	
T_A	Operating free-air temperature		-55		125	-40		85	°C

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.



V_{OL}	$V_I = V_{IH} \text{ or } V_{IL}$	$I_{OL} = 20 \mu A$	4.5 V	0.001	0.1	0.1	0.1	V
			6 V	0.001	0.1	0.1	0.1	
		$I_{OL} = 4 \text{ mA}$	4.5 V	0.17	0.26	0.4	0.33	
		$I_{OL} = 5.2 \text{ mA}$	6 V	0.15	0.26	0.4	0.33	
I_I	$V_I = V_{CC} \text{ or } 0$		6 V	± 0.1	± 100	± 1000	± 1000	nA
I_{CC}	$V_I = V_{CC} \text{ or } 0, I_O = 0$		6 V		8	160	80	μA
C_i			2 V to 6 V	3	10	10	10	pF

timing requirements over recommended operating free-air temperature range (unless otherwise noted)

			V_{CC}	$T_A = 25^\circ C$		SN54HC273		SN74HC273		UNIT
				MIN	MAX	MIN	MAX	MIN	MAX	
f_{clock}	Clock frequency		2 V		5		4		4	MHz
			4.5 V		27		18		21	
			6 V		32		21		25	
t_w	Pulse duration	\overline{CLR} low	2 V	80		120		100		ns
			4.5 V	16		24		20		
			6 V	14		20		17		
	CLK high or low		2 V	80		120		100		
			4.5 V	16		24		20		
			6 V	14		20		17		
t_{su}	Setup time before CLK \uparrow	Data	2 V	100		150		125		ns
			4.5 V	20		30		25		
			6 V	17		25		21		
	\overline{CLR} inactive		2 V	100		150		125		
			4.5 V	20		30		25		
			6 V	17		25		21		
t_h	Hold time, data after CLK \uparrow		2 V	0		0		0		ns
			4.5 V	0		0		0		
			6 V	0		0		0		

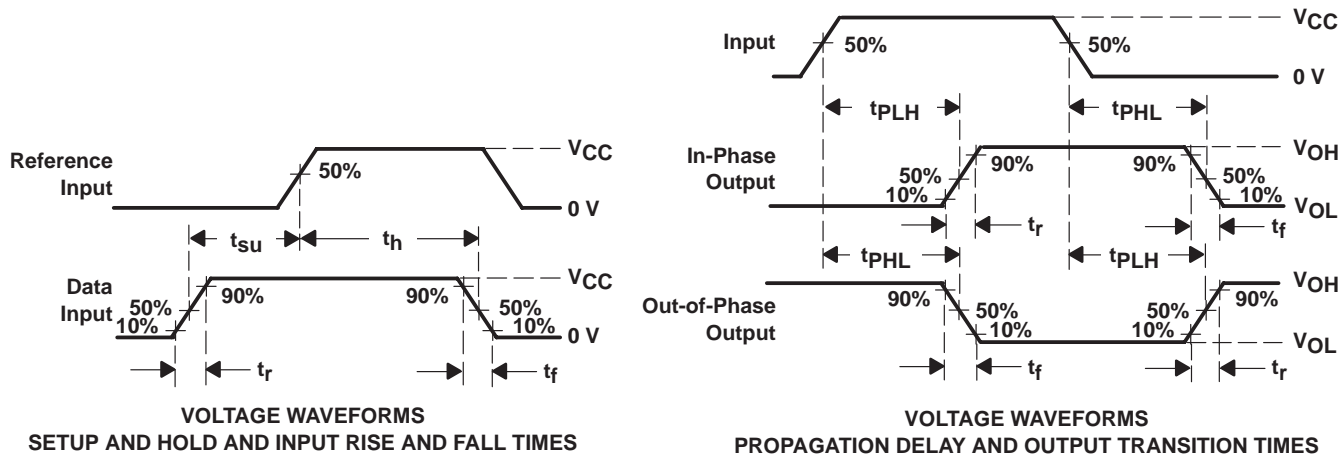


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t_{pd}	CLK	Any	2 V	56	160	240	200	ns
			4.5 V	15	32	48	40	
			6 V	13	27	41	34	
t_t		Any	2 V	38	75	110	95	ns
			4.5 V	8	15	22	19	
			6 V	6	13	19	16	

operating characteristics, T_A = 25°C

PARAMETER		TEST CONDITIONS	TYP	UNIT
C _{pd}	Power dissipation capacitance per flip-flop	No load	35	pF



- NOTES:
- A. C_L includes probe and test-fixture capacitance.
 - B. Phase relationships between waveforms were chosen arbitrarily. All input pulses are supplied by generators having the following characteristics: $PRR \leq 1 \text{ MHz}$, $Z_O = 50 \Omega$, $t_r = 6 \text{ ns}$, $t_f = 6 \text{ ns}$.
 - C. For clock inputs, f_{\max} is measured when the input duty cycle is 50%.
 - D. The outputs are measured one at a time with one input transition per measurement.
 - E. t_{PLH} and t_{PHL} are the same as t_{pD} .

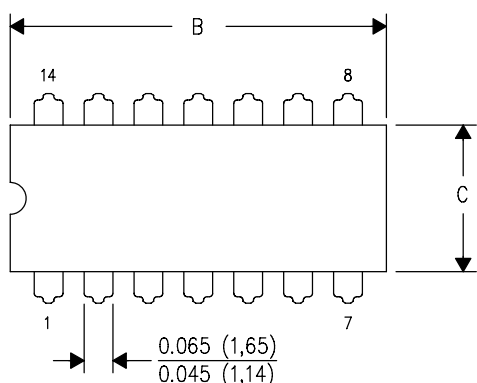
Figure 1. Load Circuit and Voltage Waveforms



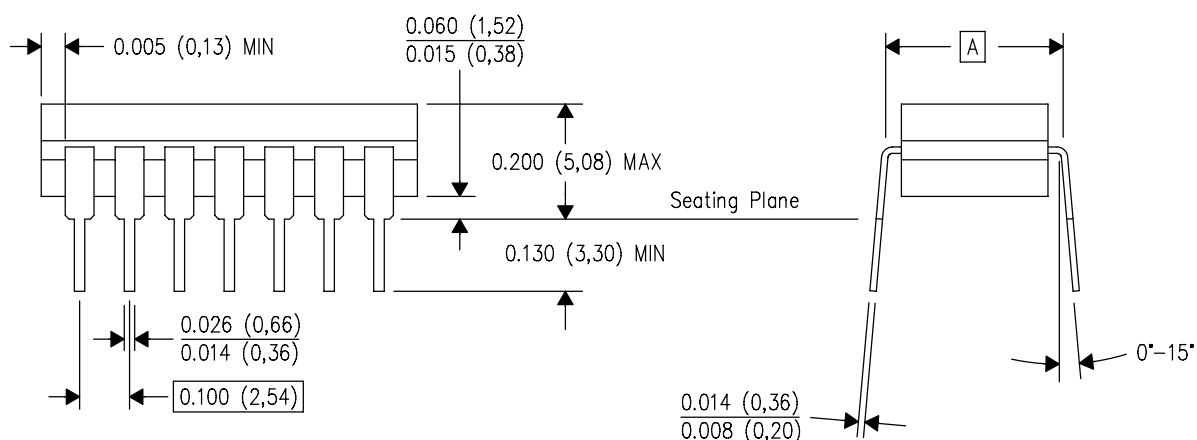
J (R-GDIP-T**)

14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



PINS ** DIM	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)

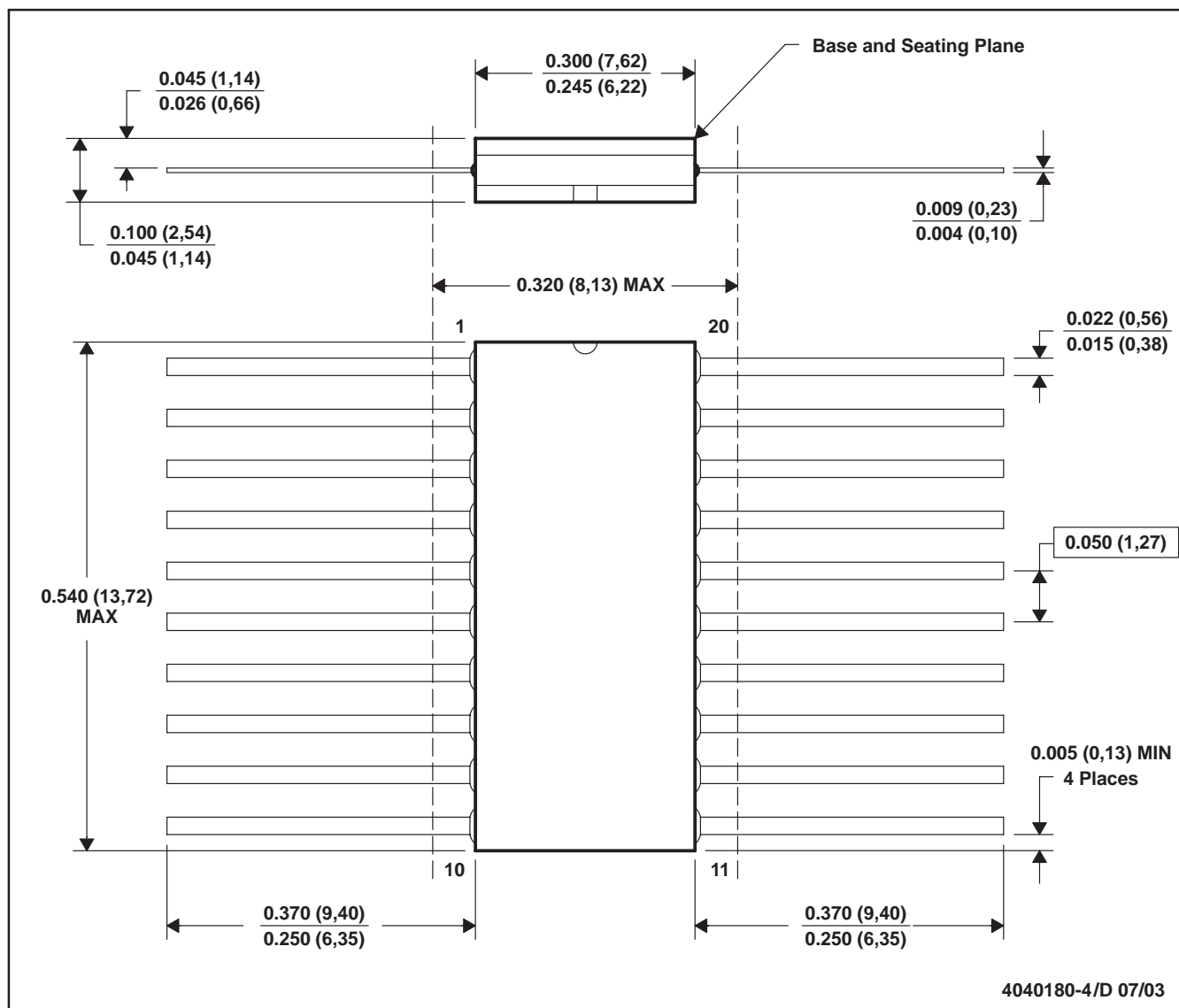


4040083/F 03/03

- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package is hermetically sealed with a ceramic lid using glass frit.
 - D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
 - E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

W (R-GDFP-F20)

CERAMIC DUAL FLATPACK

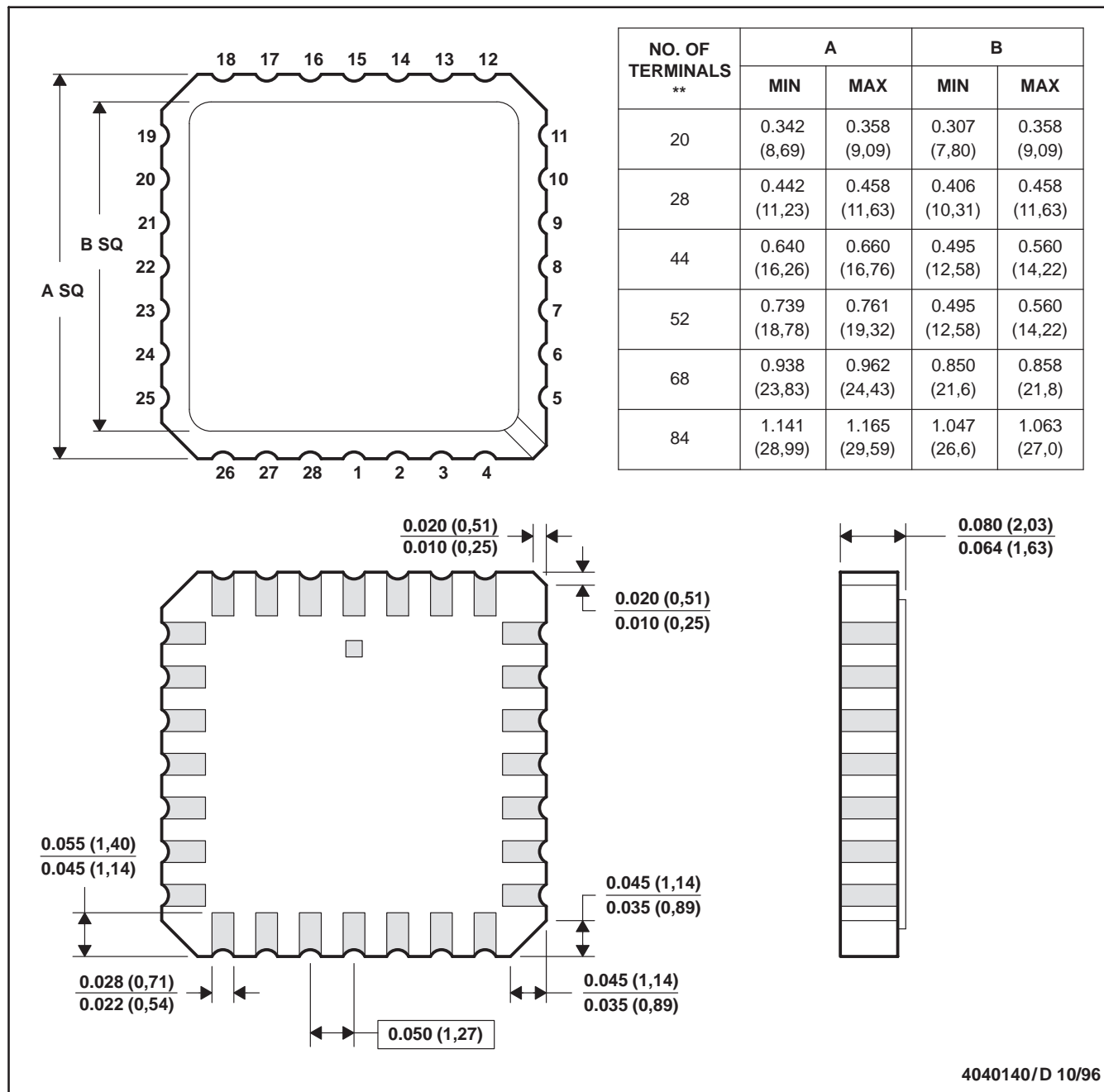


- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - This package can be hermetically sealed with a ceramic lid using glass frit.
 - Index point is provided on cap for terminal identification only.
 - Falls within Mil-Std 1835 GDFP2-F20

FK (S-CQCC-N**)

LEADLESS CERAMIC CHIP CARRIER

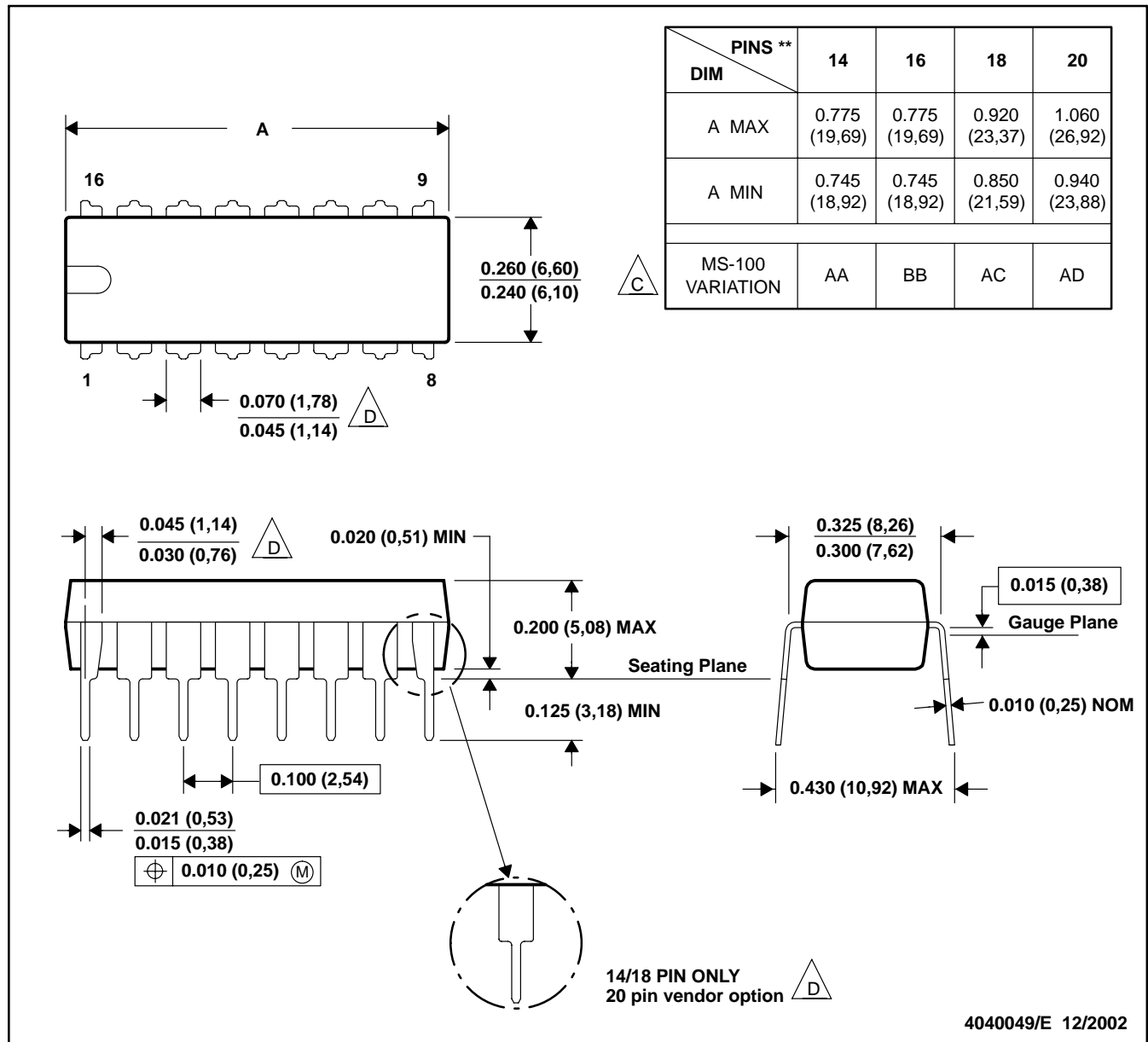
28 TERMINAL SHOWN



- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - This package can be hermetically sealed with a metal lid.
 - The terminals are gold plated.
 - Falls within JEDEC MS-004

N (R-PDIP-T)**

16 PINS SHOWN

PLASTIC DUAL-IN-LINE PACKAGE

NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

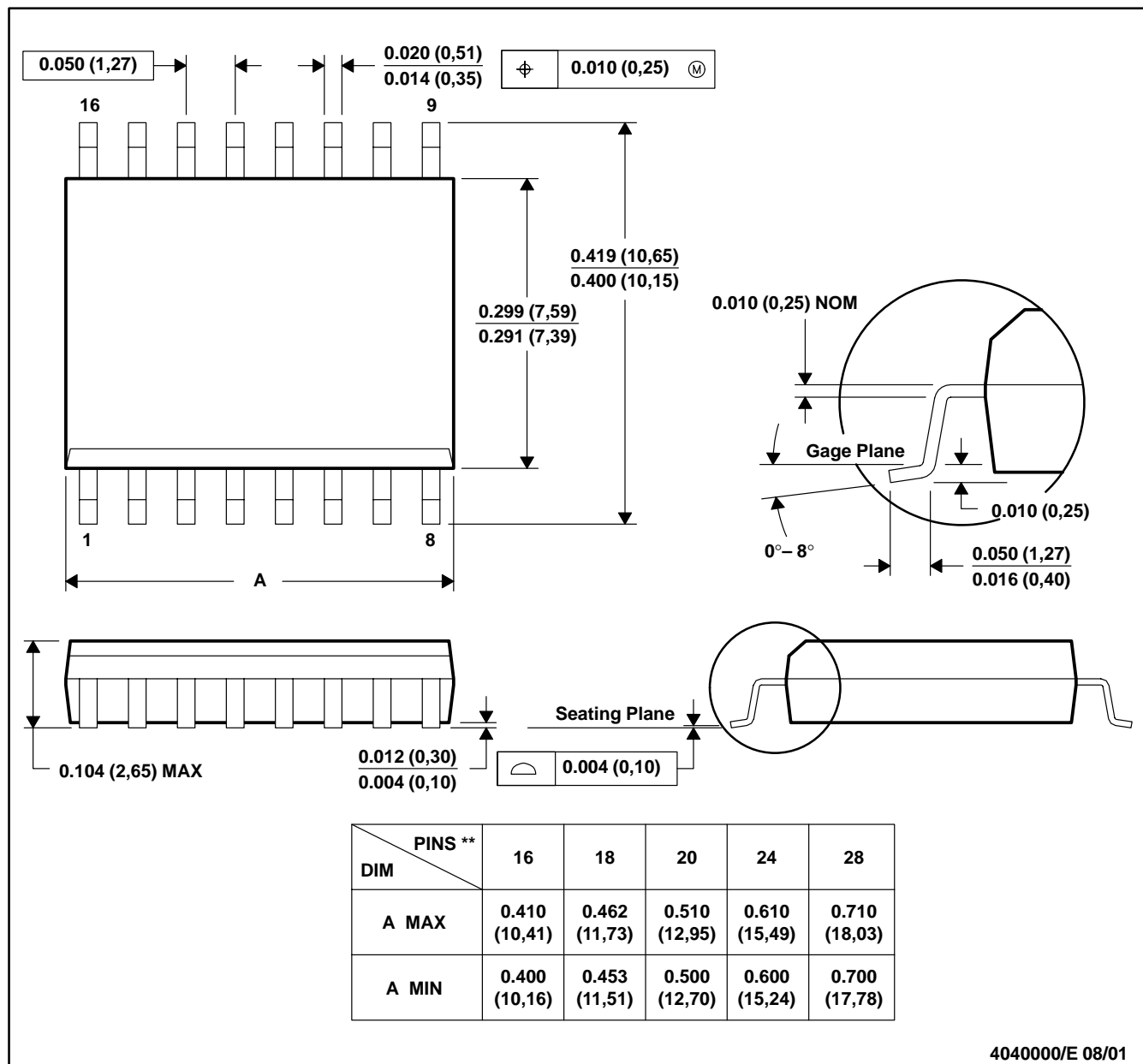
C. Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).

D. The 20 pin end lead shoulder width is a vendor option, either half or full width.

DW (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

16 PINS SHOWN



- NOTES: A. All linear dimensions are in inches (millimeters).
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
 D. Falls within JEDEC MS-013

MECHANICAL DATA

NS (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN

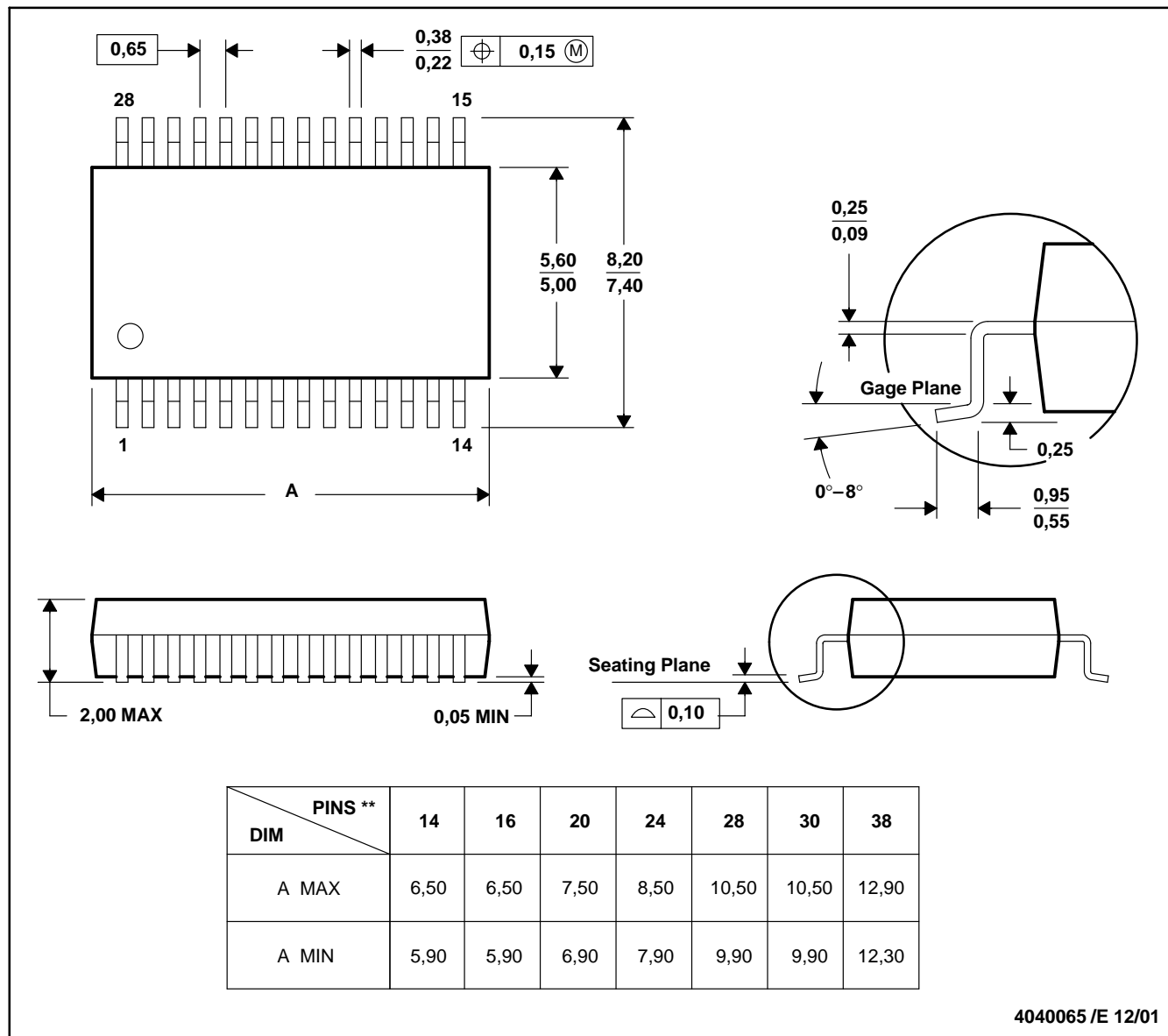


- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

DB (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

28 PINS SHOWN

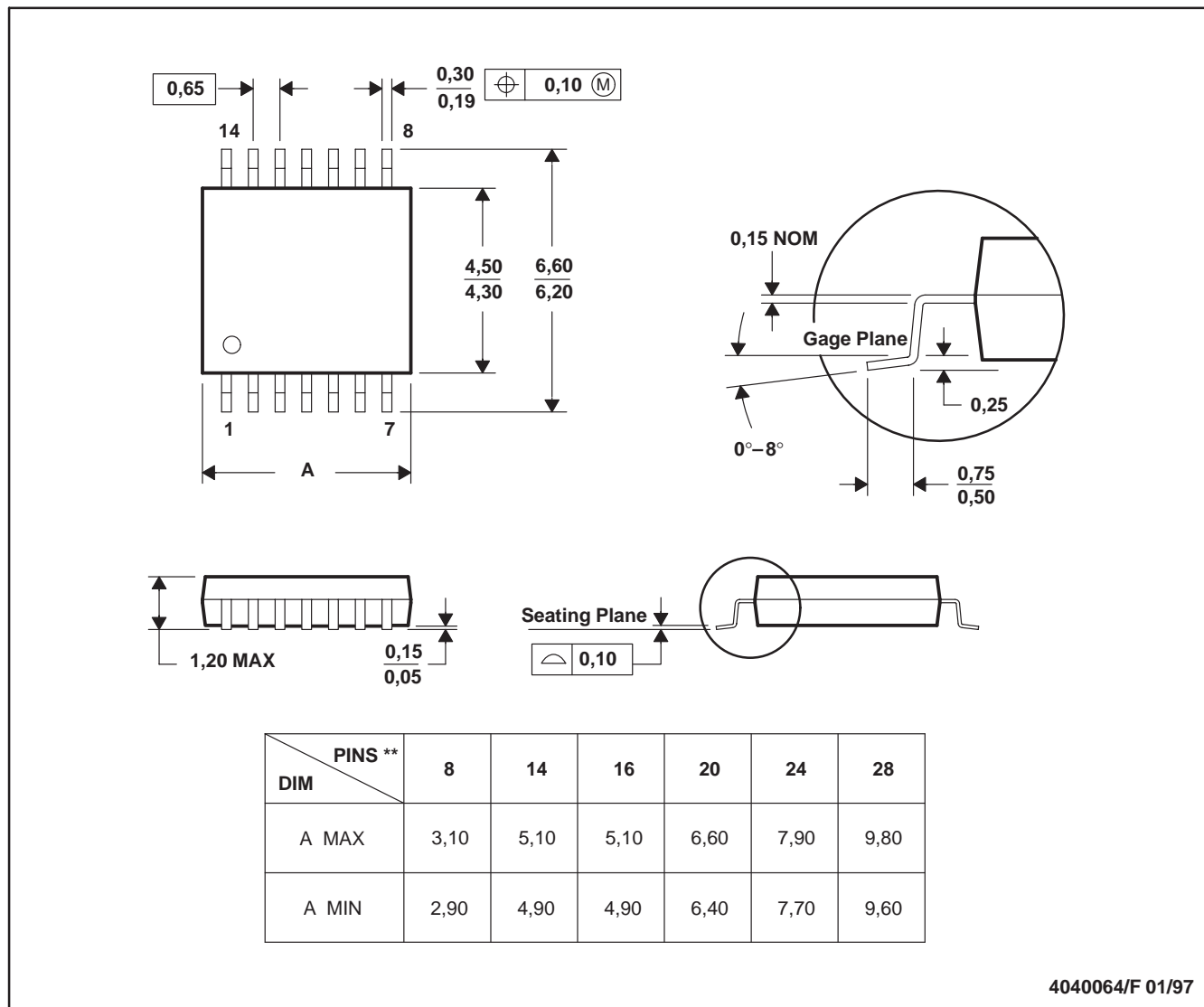


- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
 D. Falls within JEDEC MO-150

PW (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
 D. Falls within JEDEC MO-153

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